


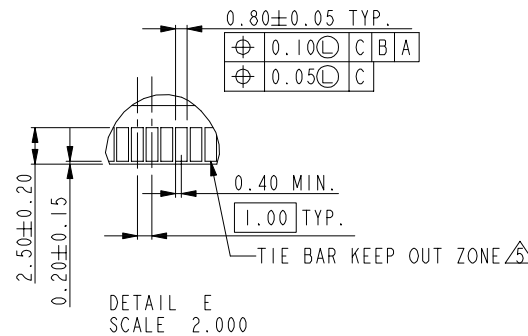
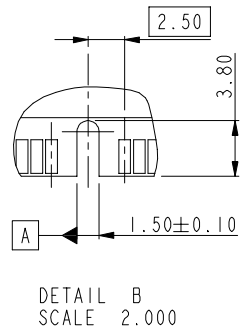
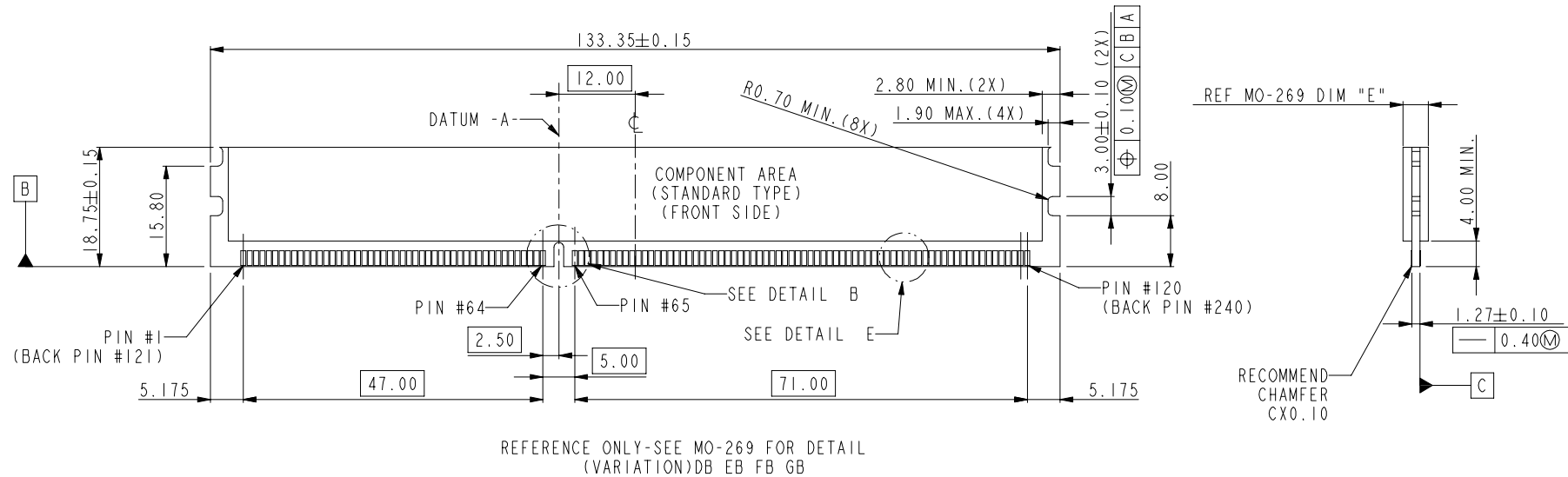





www.fciconnect.com				surface <input checked="" type="checkbox"/>		tolerance std		projection 		MM 						
				TOLERANCES UNLESS OTHERWISE SPECIFIED												
Dr	STONE	LI	05/27/2014	ANGULAR	LINEAR	0.X		±0.38	size	A4	Scale					
Eng	STONE	LI	05/27/2014			0.XX		±0.25								
Chr	ARAY	ZHANG	05/27/2014			0° ±5°	0.XXX					±0.13				
Appr	PM	ZHENG	05/27/2014	Product family					-	Spec ref			*			
				title					VERY LOW PROFILE(VLP) T.H					dwg no	10079192	Rev J
				DDR3, 240P SOCKET(FOR RDIMM MOUDLE)												
				catalog no					-							



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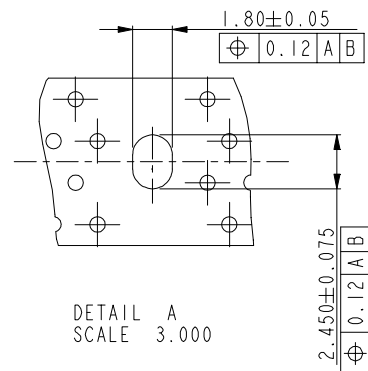
www.fciconnect.com				surface - ✓		tolerance std		projection 		MM 					
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Eng	STONE	LI	05/27/2014			0.XX		±0.25							
Chr	ARAY	ZHANG	05/27/2014	0° ±5°		0.XXX		±0.13		ECN			/		
Appr	PM	ZHENG	05/27/2014	Product family				-		Spec ref				*	
		title	VERY LOW PROFILE (VLP) T.H						dwg no			10079192		Rev.	J
			DDR3, 240P SOCKET (FOR RDIMM MOUDLE)												
			catalog no			-			CUSTOMER			sheet 2 of 4			






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REV F - 2006-04-17

RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



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				TOLERANCES UNLESS OTHERWISE SPECIFIED										
Dr	STONE	LI	05/27/2014	ANGULAR LINEAR		0.X		±0.38		size	A4	Scale	0.707	
Eng	STONE	LI	05/27/2014			0.XX		±0.25						
Chr	ARAY	ZHANG	05/27/2014	0° ±5°		0.XXX		±0.13		ECN			/	
Appr	PM	ZHENG	05/27/2014	Product family				-		Spec ref				*
				title VERY LOW PROFILE (VLP) T.H DDR3, 240P SOCKET (FOR RDIMM MOUDLE)				dwg no 10079192				Rev. J		
catalog no				-				CUSTOMER				sheet 3 of 4		



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NOTES:

1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
TERMINAL: HIGH PERFORMANCE COPPER ALLOY
METAL CLIP: COPPER ALLOY.
2. FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
3. PRODUCT SPECIFICATION: GS-12-486.
4. PACKAGING SPECIFICATION: GS-14-899.
5. FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
6. THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE. "R" MEANS FOR 'RDIMM' SOCKET.
7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.
8. THIS SOCKET MEETS APPLICABLE JEDEC STD.; SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X. (SUSPENDED BY JEDEC)
9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
10. THE HOUSING WILL WITH STAND EXPOSURE TO 260 ± 5°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.
11. AMBER EJECTOR OPTION IS ONLY FOR SOLDERING ENVIRONMENT TEMP. UNDER 170°C.
12. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.
13. THIS SOCKET CONTACT EOL RESISTANCE IS DESIGNED TO BE 20 mohm MAX.

10079192 - □ □ □ □

STYLE : MECHANICAL KEYING

I : 1.5 VOLT. W/ CENTER KEY

CONTACT & FORKLOCK LENGTH




CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 mm (0.063")
11	3.18 mm	4.00 mm	2.36 mm (0.093")

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
2LF	15u" (0.38um) MIN. GOLD	100u" (2.54um) MIN. 100% MATTE TIN	50u" (1.27um) MIN. NICKEL OVERALL
3LF	30u" (0.76um) MIN. GOLD		
4LF	3u" (0.076um) MIN. GOLD		

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
1 : BLACK HOUSING + AMBER EJECTOR (NOTE. 11)
2 : BLACK HOUSING + BLACK EJECTOR
8 : IVORY HOUSING + IVORY EJECTOR
9 : IVORY HOUSING + BLACK EJECTOR
3 : BLUE HOUSING + IVORY EJECTOR ⚠

www.fciconnect.com				surface - <input checked="" type="checkbox"/>		tolerance std		projection 		MM 	
				TOLERANCES UNLESS OTHERWISE SPECIFIED							
Dr	STONE	LI	05/27/2014	ANGULAR LINEAR		0.X		±0.38		size A4	Scale 1.000
Eng	STONE	LI	05/27/2014			0.XX		±0.25			
Chr	ARAY	ZHANG	05/27/2014	0° ±5°		0.XXX		±0.13		ECN /	
Appr	PM	ZHENG	05/27/2014	Product family				-		Spec ref *	
		title	VERY LOW PROFILE (VLP) T.H					drg no 10079192			Rev. J
			DDR3, 240P SOCKET (FOR RDIMM MOUDLE)								
			catalog no					-			CUSTOMER